

Title (en)

ENCAPSULATED ORGANIC-ELECTRONIC COMPONENT, METHOD FOR PRODUCING THE SAME AND USE THEREOF

Title (de)

VERKAPSELTES ORGANISCH-ELEKTRONISCHES BAUTEIL, VERFAHREN ZU SEINER HERSTELLUNG UND SEINE VERWENDUNG

Title (fr)

COMPOSANT ELECTRONIQUE ORGANIQUE ENCAPSULE, SON PROCEDE DE PRODUCTION ET SON UTILISATION

Publication

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Application

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- DE 10120685 A 20010427
- DE 10120687 A 20010427

Abstract (en)

[origin: WO0215264A2] The invention relates to an electronic circuit (1), comprising electronic components (3) which consist especially of organic material. Said component(s) (3) are situated between at least two layers (2, 2') forming a barrier, and are protected against the influence of light and/or air and/or water by these layers. Electronic circuits constructed in this way enable (RFID) tags to be mass produced.

IPC 1-7

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IPC 8 full level

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CPC (source: EP US)

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C-Set (source: EP US)

H01L 2924/0002 + H01L 2924/00

Citation (examination)

- US 5874804 A 19990223 - ROGERS STEPHEN P [US]
- EP 0741419 A2 19961106 - MOTOROLA INC [US]

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

WO 0215264 A2 20020221; WO 0215264 A3 20020425; EP 1309994 A2 20030514; JP 2004506985 A 20040304; US 2004026689 A1 20040212; US 7875975 B2 20110125

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